

WE CLAIM:

1. A thermal head comprising:

a thermal radiating substrate;

a temperature keeping layer formed on the thermal radiating

substrate;

a conductive layer formed on the thermal radiating substrate and
an upper surface of the temperature keeping layer comprised of a fused
material of nitride and metal or a fused material of oxide and metal;

a first interlayer insulation layer formed by oxidization of the
conductive layer except a portion of the conductive layer corresponding to a
common electrode and a portion of the common electrode corresponding to
an external connecting common electrode terminal;

a second interlayer insulation layer comprised of insulating
ceramics formed on the upper surface of the first interlayer insulation layer;

a heat generating resistor member formed above the second
interlayer insulation layer and the conductive layer;

a common electrode and individual electrodes formed at a part
of the upper surface of the heat generating resistor member; and

a protecting layer covering the heat generating resistor member,
common electrode, individual electrodes and second interlayer insulation
layer.

2. A thermal head according to Claim 1, wherein the second
interlayer insulation layer is formed by insulating ceramics comprised of at
least one of silicon nitride, silicon oxide, aluminum nitride or aluminum oxide.

3. A thermal head according to Claim 1, wherein at least more than
three common electrode terminals of the common electrode for the external
connection are formed in the thermal radiating substrate.

4. A thermal head according to Claim 1, wherein cutting planes of
the temperature keeping layer, conductive layer, first interlayer insulation
layer, second interlayer insulation layer and protecting layer at the cutting

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a protecting layer covering the heat generating resistor member, common electrode, individual electrodes and second interlayer insulation layer.

7. A thermal head according to Claim 6, wherein the metal of high melting point is tantalum.

8. A thermal head comprising;
a thermal radiating substrate;
a temperature keeping layer formed on the thermal radiating substrate;

a conductive layer formed on the thermal radiating substrate, wherein the conductive layer being formed of conductive ceramics comprised of boride, nitride, carbide or silicide of high melting point metal;

a first interlayer insulation layer formed by oxidization of the surface of the conductive layer except a portion of the conductive layer corresponding to a common electrode and a portion of the common electrode corresponding to an external connecting common electrode terminal;

a second interlayer insulation layer comprised of insulating ceramics formed on the upper surface of the first interlayer insulation layer;

a heat generating resistor member formed above the second interlayer insulation layer and the conductive layer;

a common electrode and individual electrodes formed at a part of the upper surface of the heat generating resistor member; and

a protecting layer covering the heat generating resistor member, common electrode, individual electrodes and second interlayer insulation layer.